534267-2 - ACTIVE

AMPMODU | AMPMODU IV/V

TE Internal #: 534267-2 PCB Mount Receptacle, Vertical, Board-to-Board, 20 Position, .1 in [2.54 mm] Centerline, Gold, Through Hole - Solder, Signal, Black, AMPMODU IV/V

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PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **20**

Number of Rows: 2

Features

Product Type Features

Applied Pressure

PCB Connector Assembly Type

Connector System

Standard

PCB Mount Receptacle

Board-to-Board



Sealable	No		
Connector & Contact Terminates To	Printed Circuit Board		
Configuration Features			
Stackable	Yes		
PCB Mount Orientation	Vertical		
Number of Positions	20		
Number of Rows	2		
Board-to-Board Configuration	Parallel		
Electrical Characteristics			
Dielectric Withstanding Voltage (Max)	750 VAC		
Insulation Resistance	5000 MΩ		
Operating Voltage	333 VAC		
Body Features			
Connector Profile	Low		
Primary Product Color	Black		

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Contact Features

Contact Mating Area Length	2.54 mm[.1 in]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 7.62 µm
Contact Shape & Form	Short Point
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Socket
Contact Type Contact Current Rating (Max)	Socket 3 A
Contact Current Rating (Max)	
Contact Current Rating (Max) Termination Features	3 A
Contact Current Rating (Max) Termination Features Rectangular Termination Post & Tail Thickness	3 A .2 mm[.008 in]
Contact Current Rating (Max) Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width	3 A .2 mm[.008 in] .7 mm[.028 in]

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Mating Alignment	Without		
PCB Mount Retention	Without		
PCB Mount Alignment	Without		
Connector Mounting Type	Board Mount		
Housing Features			
Mating Entry Location	Bottom & Top		
Centerline (Pitch)	2.54 mm[.1 in]		
Housing Material	Polyester - GF		
Dimensions			
Connector Height	6.2 mm[.245 in]		
Connector Height Row-to-Row Spacing	6.2 mm[.245 in] 2.54 mm[.1 in]		
Row-to-Row Spacing	2.54 mm[.1 in]		
Row-to-Row Spacing Stack Height	2.54 mm[.1 in] 2.29 mm[.09 in]		

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Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	22
Packaging Type	Box, Tube
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224)

Candidate List Declared Against: JAN 2021

(211)

SVHC > Threshold:

Pb (13% in Component Part)

Article Safe Usage Statements:

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Not Low Halogen - contains Br or Cl > 900 ppm.

Wave solder capable to 240°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

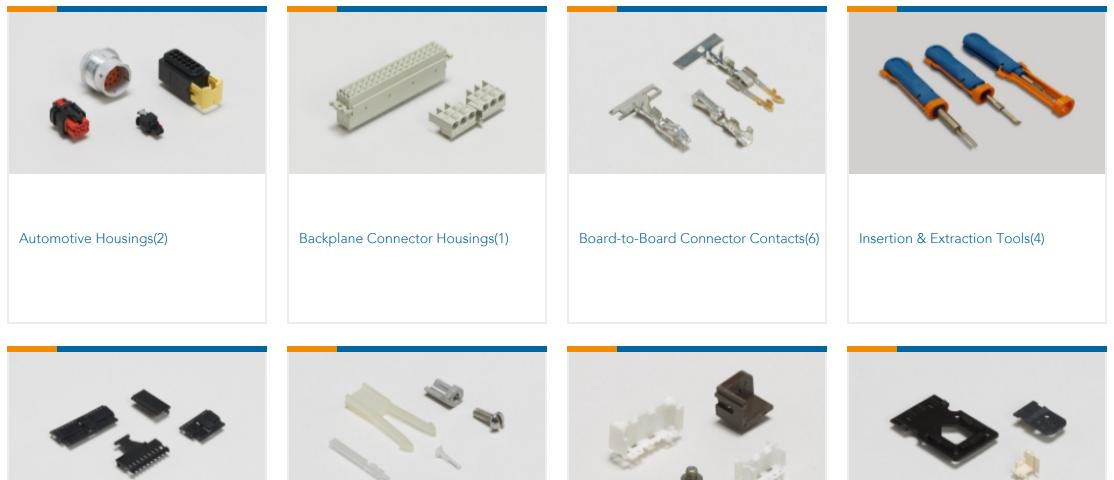
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Compatible Parts



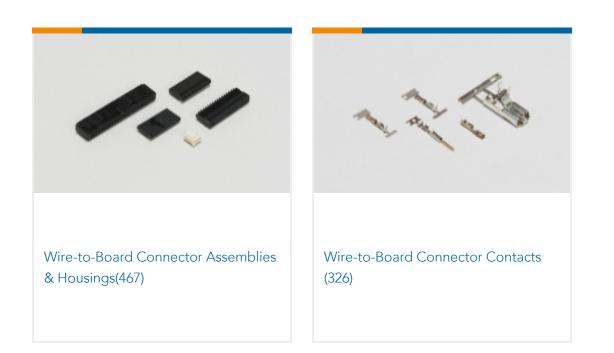
Also in the Series | AMPMODU IV/V



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PCB Connector Covers(18)	PCB Connector Keying(6)	PCB Connector Mounting(1)	PCB Connector Strain Relief(3)
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PCB Headers & Receptacles(939)	PCB Latches, Locks & Retainers(9)	Rectangular Connector Housings(5)	Standard Rectangular Connectors(8)

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Customers Also Bought



Documents

Product Drawings 20 MODIV VRT DR OE 100/125

English



CAD Files

Customer View Model

ENG_CVM_534267-2_AB.2d_dxf.zip

English

3D PDF

English

Customer View Model

ENG_CVM_534267-2_AB.3d_igs.zip

English

Customer View Model ENG_CVM_534267-2_AB.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English